L Number	Hits	Search Text	DB	Time stamp
9	1943		USPAT;	2004/10/11 12:43
			US-PGPUB;	
			EPO; JPO	
10	147	(card or carrier) with chlorine with	USPAT;	2004/10/11 12:44
		(sheet or core or layer)	US-PGPUB;	
		[	EPO; JPO	
11	2		USPAT;	2004/10/11 12:45
]		(sheet or core or layer) and card.ti.	US-PGPUB;	
12	_	(and an anniary with the state of	EPO; JPO	2004/10/31 12 /2
12	6	,	USPAT;	2004/10/11 12:47
		card.ti.	US-PGPUB; EPO; JPO	
13	1	4879153.pn.	USPAT;	2004/10/11 12:48
13	1	10,2103.pit.	US-PGPUB;	2004/10/11 12.40
			EPO; JPO	
14	350	card.ti. and (sheet or core or layer or	USPAT;	2004/10/11 13:18
		film) with (terephthalic or	US-PGPUB;	
		cyclohexanedimethanol or glycol or	EPO; JPO	
		polycarbonate)		
15	116		USPAT;	2004/10/11 13:04
		film) with (terephthalic or	US-PGPUB;	
		cyclohexanedimethanol or glycol or	EPO; JPO	
		polycarbonate) and (hole or recess or		
	_	cavity)		
16	5	1,	USPAT;	2004/10/11 13:04
		near5 core with (terephthalic or	US-PGPUB;	
		cyclohexanedimethanol or glycol or	EPO; JPO	
		polycarbonate) and (hole or recess or cavity)		
64	49	1	USPAT;	2004/10/11 13:09
``	7.7	or recess or cavity) same (chip or ic or	US-PGPUB;	2004/10/11 13:09
		processor)	EPO; JPO	
67	1	<del>*</del>	USPAT;	2004/10/11 13:13
		<u>-</u>	US-PGPUB;	
			EPO; JPO	
68	196	1	USPAT;	2004/10/11 13:19
	4	same (cavity or recess or hole)	US-PGPUB;	
1 1			EPO; JPO	
73	92		USPAT;	2004/10/11 13:28
		(antenna or coil) same insulat\$4 with	US-PGPUB;	
74	1	substrate 6440773.pn.	EPO; JPO	2004/10/11 13:31
' -	т	0330110.pm.	USPAT; US-PGPUB;	2004/10/11 13:31
			EPO; JPO	
76	10	card with (recess or cavity) with (chip or	USPAT;	2004/10/11 13:32
		module or processor or microprocessor)	US-PGPUB;	
		same plate with (reinforc\$4 or protect\$4)	EPO; JPO	
77	321		USPAT;	2004/10/11 13:33
		(chip or module or processor or	US-PGPUB;	
		microprocessor) same (antenna or coil)	EPO; JPO	
78	34	,	USPAT;	2004/10/11 13:33
		(chip or module or processor or	US-PGPUB;	
		microprocessor) same (antenna or coil)	EPO; JPO	
170	0.0	same insulat\$4		0004/10/11 10 55
79	96	, (	USPAT;	2004/10/11 13:36
		contact") and (recess or cavity) same	US-PGPUB;	
80	44	(chip or IC or processor or module) 235/492.ccls. and (contactless or "non	EPO; JPO	2004/10/11 13:42
"	44	contact") and (recess or cavity) same	USPAT; US-PGPUB;	2004/10/11 13:42
		(chip or IC or processor or module) same	EPO; JPO	
		(antenna or coil)	510, 510	
81	5		USPAT;	2004/10/11 13:44
		<u></u>	US-PGPUB;	,,
			EPO; JPO	
82	108	card same "reinforcing plate"	USPAT;	2004/10/11 13:44
			US-PGPUB;	
			EPO; JPO	
83	83	card with "reinforcing plate"	USPAT;	2004/10/11 13:50
			US-PGPUB;	
			EPO; JPO	I i

	· · · · · · · · · · · · · · · · · · ·			
84.	25	card same (hole or cavity or recess) same "reinforcing plate"	USPAT; US-PGPUB;	2004/10/11 13:50
97	1	card same multilayer near5 (sheet or core) same (antenna or coil) same (chip or ic or	EPO; JPO USPAT; US-PGPUB;	2004/10/11 14:06
98	46	module or processor) card same multilayer near5 (sheet or core)	EPO; JPO USPAT; US-PGPUB;	2004/10/11 14:06
146	49	( , ,	EPO; JPO USPAT; US-PGPUB:	2004/10/11 15:10
149	8	US-5105074-\$ or US-4814591-\$ or US-6352604-\$ or US-6180434-\$ or US-5809633-\$ or US-5304513-\$ or US-6764014-\$ or US-6709889-\$ or US-6677186-\$ or US-6607135-\$ or US-6412701-\$ or US-5969951-\$ or US-4879153-\$ or US-6283378-\$ or US-5346576-\$ or US-5026452-\$ or US-6719206-\$ or US-5013900-\$ or US-4843225-\$ or US-5701002-\$ or US-5852289-\$ or US-6352767-\$ or US-20040177215-\$ or US-20040193774-\$ or US-20040177215-\$ or US-20040169086-\$ or US-20040177215-\$ or US-20040169086-\$ or US-20040126690-\$ or US-20040161690-\$ or US-20040126690-\$ or US-20040171192-\$ or US-20030169574-\$ or US-20030171192-\$ or US-20030038174-\$ or US-20030214794-\$ or US-20030038174-\$ or US-20030057536-\$ or US-20030038174-\$ or US-20030057536-\$ or US-2004012967-\$ or US-20010015382-\$ or US-20040129788-\$ or US-20010040186-\$).did. or (JP-09050503-\$ or JP-2003242475-\$ or JP-2003034009-\$ or JP-2003163624-\$).did. or (JP-09050503-\$ or JP-2003163624-\$).did. or JP-2003034009-\$ or JP-2003040129788-\$ or US-6352604-\$ or US-6480733-\$ or US-690951-\$ or US-5168151-\$ or US-690951-\$ or US-6440733-\$ or US-690951-\$ or US-6440733-\$ or US-690951-\$ o	USPAT; US-PGPUB; EPO; JPO	2004/10/11 15:10
-	840	US-5969951-\$ or US-4879153-\$ or US-6283378-\$ or US-5346576-\$ or US-5026452-\$ or US-6719206-\$ or US-5013900-\$ or US-4843225-\$ or US-5701002-\$ or US-5888624-\$).did. or US-6352767-\$ or US-5888624-\$).did. or (US-20040193774-\$ or US-20040177215-\$ or US-20040056083-\$ or US-20040026518-\$ or US-20040169086-\$ or US-20040026518-\$ or US-20030178495-\$ or US-20030169574-\$ or US-20040161690-\$ or US-20040126690-\$ or US-20040171192-\$ or US-20030038174-\$ or US-20030214794-\$ or US-200300226901-\$ or US-20030057536-\$ or US-2004012967-\$ or US-20010015382-\$ or US-20040129788-\$ or US-20010040186-\$).did. or (JP-09050503-\$ or JP-2003242475-\$ or JP-200303409-\$ or JP-2002163624-\$).did.) and multilayer (card or carrier or tag or id or RFID or	USPAT;	2004/10/07 12:21
		identification) with clock with (speed or frequency) near5 (chang\$4 or adjust\$4 or increas\$4 or decreas\$4 or alter\$4 or modif\$9 or speed\$4 or slow\$4 or rais\$4 or	US-PGPUB; EPO; JPO	
-	23	lower\$4) (card or carrier or tag or id or RFID or identification) with clock with (speed or frequency) near5 (chang\$4 or adjust\$4 or increas\$4 or decreas\$4 or alter\$4 or modif\$9 or speed\$4 or slow\$4 or rais\$4 or lower\$4) same (display\$4 or screen or lcd	USPAT; US-PGPUB; EPO; JPO	2004/10/07 13:02
		or "liquid crystal")		
		· · · · · · · · · · · · · · · · · · ·	<del></del>	

	2	("5684672" "5598174").pn.	USPAT; US-PGPUB;	2004/10/07 14:07
-	139079	427/\$.ccls.	EPO; JPO USPAT; US-PGPUB;	2004/10/07 14:08
  -  -	84838 501	427/\$.ccls. card with display\$4 with clock	EPO; JPO USPAT USPAT;	2004/10/07 14:10 2004/10/07 14:11
_		card with display\$4 with clock near5	US-PGPUB; EPO; JPO USPAT;	2004/10/07 17:28
·		(frequency or speed)	US-PGPUB; EPO; JPO	
-	1	card near5 (smart or ic or chip or "integrated circuit") same (total\$4 or sum\$4 or combin\$4) with height with (hole)	USPAT; US-PGPUB; EPO; JPO	2004/10/07 17:30
-	0 24	20040159709.URPN. card near5 (smart or ic or chip or "integrated circuit") same (total\$4 or	USPAT USPAT; US-PGPUB;	2004/10/07 17:30 2004/10/07 17:31
_	117	sum\$4 or combin\$4) with height card near5 (smart or ic or chip or "integrated circuit") same (total\$4 or	EPO; JPO USPAT; US-PGPUB;	2004/10/07 17:39
_	38	sum\$4 or combin\$4) with thick\$4	EPO; JPO USPAT; US-PGPUB;	2004/10/07 17:46
_	226	sum\$4 or combin\$4) with thick\$4 with (layer or film or core or sheet) card near5 (smart or ic or chip or	EPO; JPO USPAT;	2004/10/07 17:56
_	227	"integrated circuit") with ("through hole") (235/\$.ccls.) and (card near5 (smart or ic	US-PGPUB; EPO; JPO USPAT;	2004/10/07 18:15
		or chip or "integrated circuit" or processor) with ("through hole" or cavity or hole) with (chip or ic or circuit or	US-PGPUB; EPO; JPO	
-	14	processor)) (235/\$.ccls.) and (card near5 (smart or ic or chip or "integrated circuit" or processor) with ("through hole" or cavity	USPAT; US-PGPUB; EPO; JPO	2004/10/07 18:18
-		or hole) with (chip or ic or circuit or processor) same reinforc\$4)	-	
-	3	(235/\$.ccls.) and (card near5 (smart or ic or chip or "integrated circuit" or processor) with ("through hole" or cavity or hole) with (chip or ic or circuit or processor) with flush)	USPAT; US-PGPUB; EPO; JPO	2004/10/07 18:19
-	46		USPAT; US-PGPUB; EPO; JPO	2004/10/07 18:24
-	17		USPAT; US-PGPUB; EPO; JPO	2004/10/07 18:28
_	50	card same (antenna or coil) same (reinforc\$4 or protect\$4) same (cavity or hole or recess) same (chip or ic or	USPAT; US-PGPUB; EPO; JPO	2004/10/07 18:38
_	168	circuit or processor) card near5 (chip or ic or circuit or processor or smart) same (antenna or coil) same (core or layer or film) same (cavity	USPAT; US-PGPUB; EPO; JPO	2004/10/08 11:59
_	80	or hole or recess) 235/\$.ccls. and card same (chip or ic or processor or circuit) same insulat\$4 same	USPAT; US-PGPUB;	2004/10/08 12:00
-	16	(antenna or coil) 235/\$.ccls. and card same (chip or ic or processor or circuit) same insulat\$4 same (antenna or coil) same (reinforc\$4 or	EPO; JPO USPAT; US-PGPUB; EPO; JPO	2004/10/08 12:04
_	2	plate) card same (chip or ic or processor or circuit) same insulat\$4 same (antenna or	USPAT; US-PGPUB;	2004/10/08 12:05
		<pre>coil) same core same (cavity or hole or recess)</pre>	EPO; JPO	

			_	
,	21	card same (chip or ic or processor or	USPAT;	2004/10/08 12:08
ľ		circuit) same insulat\$4 same (antenna or	US-PGPUB;	
		coil) same core	EPO; JPO	
-	363		USPAT;	2004/10/08 12:14
		circuit) same insulat\$4 same (antenna or	US-PGPUB;	
		coil)	EPO; JPO	
-	3		USPAT;	2004/10/08 12:16
		circuit or smart) same resin same (cavity	US-PGPUB;	
		or hole or recess) same insulat\$4 same	EPO; JPO	
		(core)		
-	4814		USPAT;	2004/10/08 12:16
		circuit or smart) same (cavity or hole or	US-PGPUB;	
		recess)	EPO; JPO	
-	98		USPAT;	2004/10/08 13:58
		circuit or smart) same (cavity or hole or	US-PGPUB;	
		recess) and (reinforc\$4 or protect\$4)	EPO; JPO	
	20	near3 plate	HCDNM.	2004/10/00 14:04
-	39	,	USPAT;	2004/10/08 14:04
		(resin or binder or adhesive or filler or	US-PGPUB;	
	24	glue)	EPO; JPO	2004/10/08 14:05
-	24	,	USPAT;	2004/10/08 14:05
		same core same (resin or binder or	US-PGPUB;	
		adhesive or filler or glue) and (contactless or "non contact" or wireless)	EPO; JPO	
1_	836		USPAT;	2004/10/08 14:09
-	636	same (terephthalic or	US-PGPUB;	2004/10/08 14:09
		cyclohexanedimethanol or glycol or	EPO; JPO	
		polycarbonate)	EFO, 0PO	
_	80		USPAT;	2004/10/08 14:10
		or processor) same (layer or sheet or film	US-PGPUB;	2004/10/08 14.10
		or core) same (terephthalic or	EPO; JPO	
		cyclohexanedimethanol or glycol or	1210, 010	
		polycarbonate)		
-	3	card near5 (smart or chip or ic or circuit	USPAT;	2004/10/08 14:11
		or processor) same (layer or sheet or film	US-PGPUB;	=====================================
		or core) same (chlorine)	EPO; JPO	
_	11		USPAT;	2004/10/08 14:12
	_	or processor) same (chlorine)	US-PGPUB;	
			EPO; JPO	
_	57	card same (chlorine)	USPAT;	2004/10/08 14:21
			US-PGPUB;	:
1			EPO; JPO	!
-	105	1	USPAT;	2004/10/08 14:22
		or protect)	US-PGPUB;	:
			EPO; JPO	
-	69	card same plate with chip with (reinforc\$6	USPAT;	2004/10/08 14:28
		or protect)	US-PGPUB;	
		, , , , , , , , , , , , , , , , , , ,	EPO; JPO	0004405455
-	9		USPAT;	2004/10/08 14:31
		or protect) same (hole or cavity or	US-PGPUB;	
		recess)	EPO; JPO	2004/10/22 14 12
-	5	card same plate same chip same (reinforc\$6	USPAT;	2004/10/08 14:40
		or protect) same (hole or cavity or	US-PGPUB;	
		recess) same (filler or adhesive or resin) same (layer or sheet or core of film)	EPO; JPO	
1_	3		HEDAT.	2004/10/00 14:41
-	3	card with (coil or antenna) same plate with (protect\$4 or reinforc\$4) same (core	USPAT;	2004/10/08 14:41
		or layer or sheet or film or substrate)	US-PGPUB;	
		same (recess or cavity or hole) same (chip	EPO; JPO	
		or processor or module or smart or ic or		
1	1	circuit)		
1 -	7787	card same (cavity or "through hole" or	USPAT;	2004/10/08 14:52
	'''	hole or recess) same (smart or ic or chip	US-PGPUB;	2004/10/00 14.32
		or processor or circuit)	EPO; JPO	
_	61	card same (cavity or "through hole" or	USPAT;	2004/10/08 14:55
		hole or recess) same (smart or ic or chip	US-PGPUB;	
		or processor or circuit) same plate with	EPO; JPO	
		(protect\$4 or reinforc\$4)		
-	139	card same (cavity or "through hole" or	USPAT;	2004/10/08 15:06
		hole or recess) same fill\$4 with (filler	US-PGPUB;	
		or adhesive or glue or resin) same (layer	EPO; JPO	
1	1	or film or core or substrate)		1
	1	or rrrm or core or substruce,		

<b>-</b> , ,	216	card same plate with (reinforc\$4)	USPAT;	2004/10/08 15:06
		Sala Samo Placo William (20111201041)	US-PGPUB;	2001, 20, 00 20,00
	ĺ		EPO; JPO	
_	22	card same plate with (reinforc\$4) same	USPAT;	2004/10/08 15:09
		(antenna or coil) same (chip or smart or	US-PGPUB;	2001, 20, 00 20103
		ic or module or processor or circuit)	EPO; JPO	1
_	26	card same plate with (reinforc\$4) same	USPAT;	2004/10/08 15:09
		(antenna or coil)	US-PGPUB;	2001, 20, 00 10.03
		(directina of coff)	EPO; JPO	
_	152	card near4 (smart or ic or chip or	USPAT;	2004/10/08 15:16
	102	processor or circuit) same core with sheet	US-PGPUB;	2001, 20, 00 20110
		processor or effecte, same core with sheet	EPO; JPO	
_	48	card near4 (smart or ic or chip or	USPAT;	2004/10/08 15:25
	40	processor or circuit) same core with sheet	US-PGPUB;	2004/10/00 13.23
		same (recess or cavity or hole)	EPO; JPO	į
_	16	(card near4 (smart or ic or chip or	USPAT;	2004/10/08 15:26
_	1 10	processor or circuit) same core with sheet	US-PGPUB;	2004/10/08 13.20
		same (recess or cavity or hole)) and (coil	EPO; JPO	
		or antenna)	EPO; OPO	
	59	l '	HCDAM.	2004/10/08 15:58
_	) 39		USPAT;	2004/10/06 13:36
		processor) same (coil or antenna) same core with (film or layer or sheet)	US-PGPUB;	
	901		EPO; JPO	2004/10/00 15.50
-	901	1 (	USPAT;	2004/10/08 15:59
		processor) same (coil or antenna) with	US-PGPUB;	
		(core or film or layer or sheet or	EPO; JPO	
	607	substrate)	MODAM.	2004 (10 (00 15 50
_	687		USPAT;	2004/10/08 15:59
		processor) with (coil or antenna) with	US-PGPUB;	
		(core or film or layer or sheet or	EPO; JPO	
		substrate)		0004/10/00 15 50
_	98	I there is a second of the contract of the con	USPAT;	2004/10/08 15:59
		processor) with (coil or antenna) with	US-PGPUB;	
		(core or film or layer or sheet or	EPO; JPO	
		substrate) with insulat\$4		0001/10/100 10 11
_	1		USPAT	2004/10/08 16:11
-	1	1	USPAT	2004/10/08 16:12
-	21		USPAT	2004/10/08 16:18
		ic) with (substrate or core) same (cavity		
- X		or hole or recess)		0004/40/60 55
-	27	,, + + ()	USPAT	2004/10/08 16:19
		recess) same (antenna or coil) same (core		
		or layer or substrate)		
-	42	1 , ,	USPAT;	2004/10/08 16:32
		processor) with (cavity or recess or hole)	US-PGPUB;	
		with (antenna or coil)	EPO; JPO	1
-	1	6719206.pn.	USPAT	2004/10/08 16:48